



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-09-05
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antoenella Lanzafame	Representative title	AMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
L7983PU33R	3QDC*UBG8AC5	A	Z6HA	2024-09-05
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	17.50	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
LGA	3 x 3	10	Flat
Comment			
Comment	B0A4 DFN 3X3X0.8 10L PITCH 0.5		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Exemption Id.	Description	

QueryList : California Prop65 list, dated 17th Nov 2023			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			true
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			false
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-27th June 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document							Mfr Item Name	3QDC*UBG&AC5		17.5000		2006853.0	1000001.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	M-011 Other inorganic materials	1.605	mg	supplier	die	Silicon(Si)	7440-21-3		1.514	mg	943302	86514	
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.021	mg	13084	1200	
				supplier	metallisation	Copper(Cu)	7440-50-8		0.004	mg	2492	229	
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	623	57	
				supplier	metallisation	Tungsten(W)	7440-33-7		0.002	mg	1246	114	
				supplier	passivation	Silicon oxide	7631-86-9		0.040	mg	24922	2286	
				supplier	polymer coating	polyimide	proprietary		0.023	mg	14330	1314	
				supplier	UBM	Copper (Cu)	7440-50-8		1.447	mg	901558	82686	
				supplier	UBM	Titanium (Ti)	7440-32-6		0.002	mg	1246	114	
				supplier	UBM	Nickel (Ni)	7440-02-0		0.095	mg	59190	5429	
				supplier	bump	Tin (Sn)	7440-31-5		0.071	mg	44237	4057	
				supplier	bump	Silver (Ag)	7440-22-4		0.001	mg	623	57	
				Leadframe	M-004 Copper and its alloys	0.000	mg	supplier	alloy	Copper(Cu)	7440-50-8		2.107
supplier	alloy	Iron(Fe)	7439-89-6						0.048	mg	0	2743	
supplier	alloy	Phosphorus metal	7723-14-0						0.004	mg	0	229	
supplier	alloy	Zinc(Zn)	7440-66-6						0.005	mg	0	286	
supplier	glue	POLYGLYCOL ETHER	9038-95-3						0.279	mg	0	15943	
Die attach	M-011 Other inorganic materials	0.000	mg	supplier	glue	PROPRIETARY ADDITIVES	Proprietary		0.041	mg	0	2343	
				supplier	glue	PROPRIETARY ADDITIVES	Proprietary		0.041	mg	0	2343	
Encapsulation	M-011 Other inorganic materials	0.000	mg	supplier	mold compound	Epoxy Resin	Proprietary		0.296	mg	0	16914	
				supplier	mold compound	Phenol Resin	Proprietary		0.296	mg	0	16914	
				supplier	mold compound	Silica(Amorphous) A	60676-86-0		9.276	mg	0	530057	
				supplier	mold compound	Silica(Amorphous) B	7631-86-9		1.768	mg	0	101029	
				supplier	mold compound	Carbon Black	1333-86-4		0.119	mg	0	6800	
Connections coating	Solder	0.000	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.040	mg	0	2286	